



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of: Gene R. Anderson, et al.

Serial No.: 09/749,285

Group Art Unit: 2874

Filed: December 26, 2000

Examiner: Unknown

For: Housing and Mounting Structure

White & Case Docket No.: 1613370-0012

I hereby certify that this paper is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Mail Stop I.D.S. / Group Art Unit 2874, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on August 12, 2003

Christina Ishihara

Name

Signature

August 12, 2003

Date

INFORMATION DISCLOSURE STATEMENT

Mail Stop I.D.S. / Group Art Unit 2874
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In accordance with the duty of disclosure imposed by 37 C.F.R. § 1.56 to inform the Patent Office of all references coming to the attention of Applicants or attorneys or agents for Applicants which are or may be material to the examination of the subject application, Attorneys for Applicants hereby invite the Examiner's attention to the reference(s) listed on the accompanying PTO Form SB/08A.

Identification of references listed on the attached PTO form is not to be construed as an admission of Applicants or attorneys for Applicants that such references are material or available as prior art against the subject application. The right is reserved to antedate any item in accordance with standard procedure.

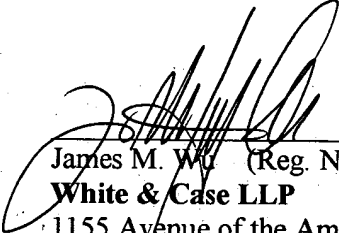
RECEIVED
AUG 18 2003
TC 2800 MAIL ROOM

This submission is understood to complement the results of the Examiner's own independent search. The submission should not be construed as a representation that a search was made, or that the cited items are inclusive of all the relevant and material citations that may be available publicly.

Copies of the cited references are enclosed. Applicants respectfully request that the Examiner review the attached references and that they be made of record in the file history of the above-captioned application.

In connection with the filing of this Information Disclosure Statement, Applicants believe that there is no fee due. However, should there be a required fee the Commissioner is hereby authorized to charge White & Case LLP Deposit Account No. 23-1703.

Dated: August 12, 2003



James M. Wu (Reg. No. 45,241)
White & Case LLP
1155 Avenue of the Americas
New York, NY 10036-2787
(650) 213-0302



Please type a plus sign (+) inside this box +

PTO/SB/08A (10-96)

Approved for use through 10/31/99. OMB 0651-0031
Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

Substitute for form 1449A/PTO				Complete if Known		
INFORMATION DISCLOSURE STATEMENT BY APPLICANT				Application Number	09/749,285	
				Filing Date	December 26, 2000	
				First Named Inventor	Gene R. Anderson	
				Group Art Unit	2874	
(use as many sheets as necessary)				Examiner Name	Unknown	
Sheet	1	of	3	Attorney Docket Number	1613370-0012	
U.S. PATENT DOCUMENTS						
Examiner Initials *	Cite No.	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	
		Number-Kind Code ² (if known)				
TL		US - 4,145,110	03-20-1979	Szentesi		
		US - 4,329,190	05-11-1982	Berg et al.		
		US - 4,479,698	10-30-1984	Landis et al.		
		US - 4,563,725	01-07-1986	Kirby		
		US - 4,709,979	12-01-1987	Spodati et al.		
		US - 4,729,623	03-08-1988	Mery		
		US - 4,730,198	03-08-1988	Brown et al.		
		US - 4,767,430	08-30-1988	Deneka et al.		
		US - 4,772,123	09-20-1988	Radner		
		US - 4,836,645	06-06-1989	Lefevre et al.		
		US - 5,054,879	10-08-1991	Brown		
		US - 5,076,688	12-31-1991	Bowen et al.		
		US - 5,214,444	05-25-1993	Kerr et al.		
		US - 5,226,052	07-06-1993	Tanaka et al.		
		US - 5,535,296	07-09-1996	Uchida		
		US - 5,539,848	07-23-1996	Galloway		
		US - 5,630,988	05-20-1997	Stolp		
		US - 5,790,733	08-04-1998	Smith et al.		
		US - 5,796,714	08-18-1998	Chino et al.		
		US - 5,818,990	10-06-1998	Steijer et al.		
		US - 5,879,173	03-09-1999	Poplawski et al.		
		US - 5,907,571	05-25-1999	Ogino et al.		
		US - 5,914,976	06-22-1999	Jayaraman et al.		
		US - 5,940,562	08-17-1999	Henson et al.		
		US - 5,963,693	10-05-1999	Mizue et al.		
		US - 5,963,696	10-05-1999	Yoshida et al.		
		US - 6,023,339	02-08-2000	Haugsjaa et al.		
		US - 6,040,624	03-21-2000	Chambers et al.		
		US - 6,170,996	01-09-2001	Miura et al.		
		US - 6,195,261	02-27-2001	Babutzka et al.		
		US - 6,217,231	04-17-2001	Mesaki et al.		
		US - 6,235,141	05-22-2001	Feldman et al.		
		US - 6,249,637	06-19-2001	Weigel		
		US - 6,250,820	06-26-2001	Melchior et al.		
		US - 6,305,848	10-23-2001	Gregory		
		US - 6,325,551	12-04-2001	Williamson III et al.		
		US - 6,354,747	03-12-2002	Irie et al.		
		US - 6,396,191	05-28-2002	Hagelstein et al.		
	TL		US - 6,404,792	06-11-2002	Yamamoto et al.	

RECEIVED
AUG 18 2003
IC 2800 MAIL ROOM



FOREIGN PATENT DOCUMENTS

Examiner Initials*	Cite No. ¹	Foreign Patent Document			Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ₆
		Country Code ³	Number ⁴	Kind Code ⁵ (if known)				
TL			GB 1 304 428		01-24-1973	General Elec.		
			JP 56 046573		04-17-1981	Hitachi Ltd.		
			JP 56 079468		06-30-1981	Matsushita		
			JP 56 111822		09-03-1981	Oki Densen		
			JP 60 156023		08-16-1985	Tateishi Denki		
			JP 01 073304		03-17-1989	Furukawa Elec.		
			DE 40 02 370 A1		08-01-1991	Standard Elek.		
			EP 0 440 336 A2		08-07-1991	Amphenol Corp.		
			DE 41 23 370 A1		01-21-1993	Robock		
			JP 05 102529		04-23-1993	NEC Corp.		
			EP 0 589 622 A1		03-30-1994	American Tele.		
			JP 08 082724		03-26-1996	Fujitsu		
			JP 09 043456		02-14-1997	NEC Corp.		
			JP 09 061683		03-07-1997	Fuji Elec.		
			WO 97 25638 A3		07-17-1997	Siemens		
			WO 97 25641		07-17-1997	Siemens AG		
			JP 09 197197		07-31-1997	Furukawa Elec.		
			EP 0 790 678 A2		08-20-1997	Alcatel		
			JP 10 186162		07-14-1998	Furukawa Elec.		
			WO 98 31080		07-16-1998	W.L. Gore et al.		
			JP 10 197751		07-31-1998	Hitachi Cable		
			JP 10 126002		08-31-1998	Matsushita		
			JP 10 239569		09-11-1998	Asahi Glass Co.		
			EP 0 899 592		03-03-1999	Bosch, Robert		
			WO 99 39230		08-05-1999	Litef GmBh		
			EP 0 607 700 B1		08-25-1999	Sharp		
			WO 00 13051 A1		03-09-2000	Digital Optics		
			WO 00 46623		08-10-2000	Siemens Aktien.		
			EP 1 028 340 A1		08-16-2000	NEC Corp.		
			EP 1 028 341 A2		08-16-2000	Hewlett-Packard		
			EP 0 974 856 A2		11-02-2000	Honeywell		
TL			WO 00 73833 A1		12-07-2000	E20 Commun.		

RECEIVED
AUG 18 2003
TC 2800 MAIL ROOM



OTHER PRIOR ART – NON PATENT LITERATURE DOCUMENTS			
Examiner Initials *	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
TL		ROBINSON, et al., Low Cost Molded Packaging for Optical Data Links, 1994 IEEE Journal, pp. 312-316	
TL		NAGAHORI, et al., 1-Gbyte/sec Array Transmitter and Receiver Modules for Low-Cost Optical Fiber Interconnection, 996 Electronic Components & Technology Conference, 46 th Proceedings, pp. 255-258	
TL		NIBURG et al., A Complete Sub-System of Parallel Optical Interconnects for Telecom Applications, 1996 Electronic Components & Technology Conference, 46 th Proceedings, pp. 259-263	
TL		de PESTEL et al., Parallel Optical Interconnections for Future Broad Band Systems, Based on the "Fiber in Board Technology", 1996 Electronic Components & Technology Conference, 46 th Proceedings, pp. 264-266	
TL		WONG et al., OptoElectronic Technology Consortium (OETC) Parallel Optical Data Link Components, System Applications and Simulation Tools, 1996 Electronic Components & Technology Conference, 46 th Proceedings, pp. 269-278	
TL		LEBBY et al., Characteristics of VCSEL Arrays for Parallel Optical Interconnects, 1996 Electronic Components & Technology Conference, 46 th Proceedings, pp. 279-291	
TL		CROW et al., The Jitney Parallel Optical Interconnect, 1996 Electronic Components & Technology Conference, 46 th Proceedings, pp. 292-300	
TL		HAHN et al., Gigabyte/sec Data Communications with the POLO Parallel Optical Link, 1996 Electronic Components & Technology Conference, 46 th Proceedings, pp. 301-307	
TL		LIU et al., Polymer Optical Interconnect Technology (POINT) – Optoelectronic Packaging and Interconnect for Board and Backplane Applications, 1996 Electronic Components & Technology Conference, 46 th Proceedings, pp. 308-315	
TL		SWIRHUN et al., The P-Vixelink™ Multichannel Optical Interconnect, 1996 Electronic Components & Technology Conference, 46 th Proceedings, pp. 316-320	
TL		CARSON et al., Low-Power Modular Parallel Photonic Data Links, 1996 Electronic Components & Technology Conference, 46 th Proceedings, pp. 321-326	
TL		KIBAR et al., Power Minimization and Technology Comparisons for Digital Free-Space Optoelectronic Interconnections, 1999 Journal of Lightwave Technology, Vol. 17, No. 4, pp. 546-555	
TL		SIMONIS et al., 1 Gb/s VCSEL/CMOS Flip-Chip 2-D Array Interconnects and Associated Diffractive Optics, 1999 Parallel Interconnect (PI '99), pp. 1-9	

Examiner Signature	T L E	Date Considered	5/20/04
--------------------	-------	-----------------	---------

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹ Unique citation designation number. ² See attached Kinds of U.S. Patent Documents. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.

Burden Hour Statement: This form is estimated to take 2.0 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Assistant Commissioner for Patents, Washington, DC 20231.

RECEIVED
 AUG 18 2003
 IC 2800 MAIL ROOM